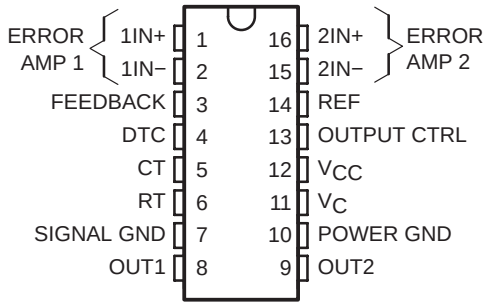
SLVS053D − FEBRUARY 1988 − REVISED NOVEMBER 2003

- **Complete PWM Power-Control Function**
- **Totem-Pole Outputs for 200-mA Sink or Source Current**
- **Output Control Selects Parallel or Push-Pull Operation**
- **Internal Circuitry Prohibits Double Pulse at Either Output**
- **Variable Dead-Time Provides Control Over Total Range**
- **Internal Regulator Provides a Stable 5-V Reference Supply, Trimmed to 1% Tolerance**
- **On-Board Output Current-Limiting Protection**
- **Undervoltage Lockout for Low-V_{CC} Conditions**
- **Separate Power and Signal Grounds**

D OR N PACKAGE
(TOP VIEW)



description/ordering information

The TL598 incorporates all the functions required in the construction of pulse-width-modulated (PWM) controlled systems on a single chip. Designed primarily for power-supply control, the TL598 provides the systems engineer with the flexibility to tailor the power-supply control circuits to a specific application.

The TL598 contains two error amplifiers, an internal oscillator (externally adjustable), a dead-time control (DTC) comparator, a pulse-steering flip-flop, a 5-V precision reference, undervoltage lockout control, and output control circuits. Two totem-pole outputs provide exceptional rise- and fall-time performance for power FET control. The outputs share a common source supply and common power ground terminals, which allow system designers to eliminate errors caused by high current-induced voltage drops and common-mode noise.

The error amplifier has a common-mode voltage range of 0 V to V_{CC} − 2 V. The DTC comparator has a fixed offset that prevents overlap of the outputs during push-pull operation. A synchronous multiple supply operation can be achieved by connecting RT to the reference output and providing a sawtooth input to CT.

The TL598 device provides an output control function to select either push-pull or parallel operation. Circuit architecture prevents either output from being pulsed twice during push-pull operation. The output frequency for push-pull applications is one-half the oscillator frequency $\left(f_O = \frac{1}{2\ RT\ CT}\right)$. For single-ended applications: $f_O = \frac{1}{RT\ CT}$.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	TL598CN	TL598CN
	SOIC (D)	Tube of 40	TL598CD	TL598C
		Reel of 2500	TL598CDR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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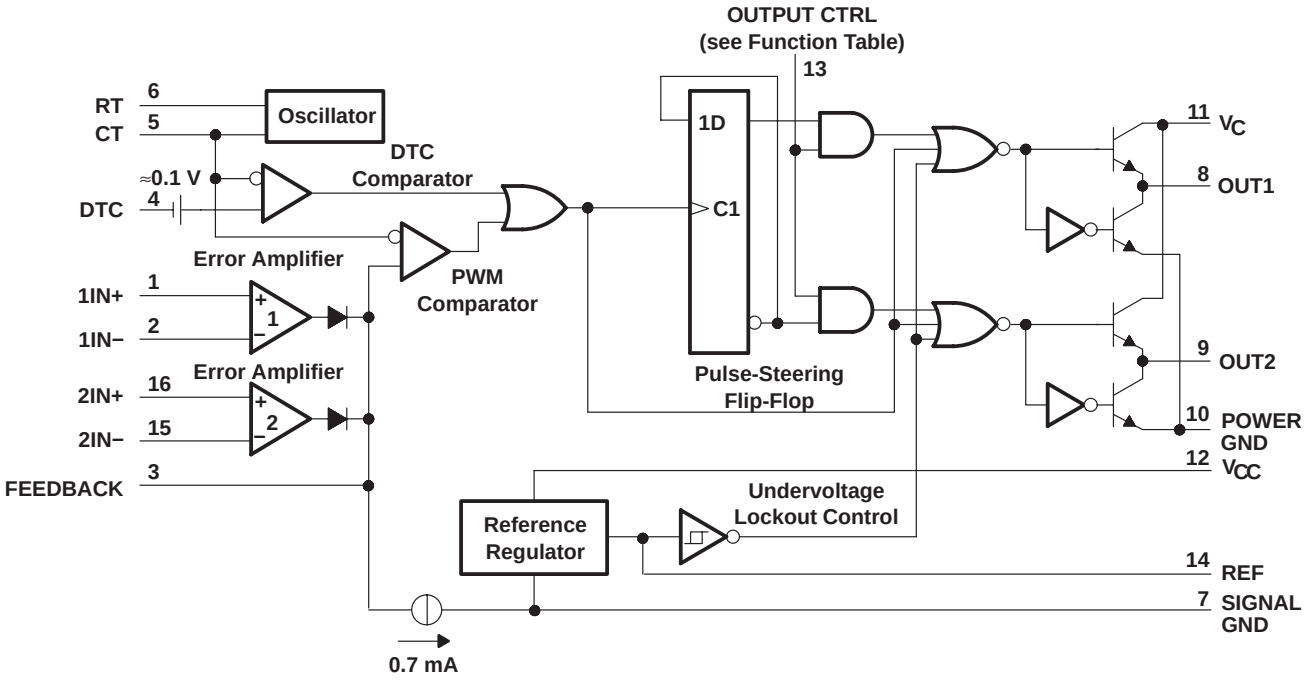
FUNCTION TABLE

INPUT/OUTPUT CTRL	OUTPUT FUNCTION
V_I = GND	Single-ended or parallel output
V_I = REF	Normal push-pull operation

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 41 V
Amplifier input voltage, V_I . . . . . V_{CC} + 0.3 V
Collector voltage . . . . . 41 V
Output current (each output), sink or source, I_O . . . . . 250 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package . . . . . 73°C/W
N package . . . . . 67°C/W
Operating virtual junction temperature, T_J . . . . . 150°C
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to the signal ground terminal.
2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V_{CC}	Supply voltage	7	40	V
V_I	Amplifier input voltage	0	$V_{CC}-2$	V
I_O	Collector voltage		40	V
I_{IL}	Output current (each output), sink or source		200	mA
	Current into feedback terminal		0.3	mA
C_T	Timing capacitor	0.00047	10	μF
R_T	Timing resistor	1.8	500	kΩ
f_{osc}	Oscillator frequency	1	300	kHz
T_A	Operating free-air temperature	0	70	°C

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 15 V (unless otherwise noted)

reference section (see Note 4)

PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
Output voltage (REF)	I_O = 1 mA	T_A = 25°C	4.95	5	5.05	V
		T_A = full range	4.9		5.1	
Input regulation	V_{CC} = 7 V to 40 V	T_A = 25°C		2	25	mV
Output regulation	I_O = 1 mA to 10 mA	T_A = 25°C		1	15	mV
		T_A = full range			50	
Output voltage change with temperature	ΔT_A = MIN to MAX			2	10	mV/V
Short-circuit output current§	REF = 0 V		−10	−48		mA

† Full range is 0°C to 70°C.
‡ All typical values, except for parameter changes with temperature, are at T_A = 25°C.
§ Duration of the short circuit should not exceed one second.
NOTE 4: Pulse-testing techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

oscillator section, C_T = 0.001 μF, R_T = 12 kΩ (see Figure 1) (see Note 4)

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
Frequency			100		kHz
Standard deviation of frequency¶	All values of V_{CC}, C_T, R_T, T_A constant		100		Hz/kHz
Frequency change with voltage	V_{CC} = 7 V to 40 V, T_A = 25°C		1	10	Hz/kHz
Frequency change with temperature#	ΔT_A = full range		70	120	Hz/kHz
	ΔT_A = full range, C_T = 0.01 μF		50	80	

† Full range is 0°C to 70°C.
‡ All typical values, except for parameter changes with temperature, are at T_A = 25°C.
¶ Standard deviation is a measure of the statistical distribution about the mean, as derived from the formula:

$$\sigma = \sqrt{\frac{\sum_{n=1}^{N} (x_n - \overline{X})^2}{N - 1}}$$

Effects of temperature on external R_T and C_T are not taken into account.
NOTE 4. Pulse-testing techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 15 V (unless otherwise noted) (continued)

error amplifier section (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input offset voltage	FEEDBACK = 2.5 V		2	10	mV
Input offset current	FEEDBACK = 2.5 V		25	250	nA
Input bias current	FEEDBACK = 2.5 V		0.2	1	µA
Common-mode input voltage range	V_{CC} = 7 V to 40 V	0 to V_{CC}−2			V
Open-loop voltage amplification	ΔV_O (FEEDBACK) = 3 V, V_O (FEEDBACK) = 0.5 V to 3.5 V	70	95		dB
Unity-gain bandwidth			800		kHz
Common-mode rejection ratio	V_{CC} = 40 V, ΔV_{IC} = 6.5 V, T_A = 25°C	65	80		dB
Output sink current (FEEDBACK)	FEEDBACK = 0.5 V	0.3	0.7		mA
Output source current (FEEDBACK)	FEEDBACK = 3.5 V	−2			mA
Phase margin at unity gain	FEEDBACK = 0.5 V to 3.5 V, R_L = 2 kΩ		65°		
Supply-voltage rejection ratio	FEEDBACK = 2.5 V, ΔV_{CC} = 33 V, R_L = 2 kΩ		100		dB

† All typical values, except for parameter changes with temperature, are at T_A = 25°C.
NOTE 4. Pulse-testing techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 15 V (unless otherwise noted)

undervoltage lockout section (see Note 4)

PARAMETER	TEST CONDITIONS‡	MIN	MAX	UNIT
Threshold voltage	T_A = 25°C	4	6	V
	ΔT_A = full range	3.5	6.9	
Hysteresis§	T_A = 25°C	100		mV
	T_A = full range	50		

‡ Full range is 0°C to 70°C.
§ Hysteresis is the difference between the positive-going input threshold voltage and the negative-going input threshold voltage.
NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

output section (see Note 4)

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
High-level output voltage	V_{CC} = 15 V, V_C = 15 V	I_O = −200 mA	12		V
		I_O = −20 mA	13		
Low-level output voltage	V_{CC} = 15 V, V_C = 15 V	I_O = 200 mA		2	V
		I_O = 20 mA		0.4	
Output-control input current	V_I = V_{ref}			3.5	mA
	V_I = 0.4 V			100	µA

NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 15 V (unless otherwise noted) (continued)

dead-time control section (see Figure 1) (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input bias current (DTC)	V_I = 0 to 5.25 V		−2	−10	μA
Maximum duty cycle, each output	DTC = 0 V	0.45			
Input threshold voltage (DTC)	Zero duty cycle		3	3.3	V
	Maximum duty cycle	0			

† All typical values, except for parameter changes with temperature, are at T_A = 25°C.
NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

pwm comparator section (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input threshold voltage (FEEDBACK)	DTC = 0 V		3.75	4.5	V
Input sink current (FEEDBACK)	$V_{(FEEDBACK)}$ = 0.5 V	0.3	0.7		mA

† All typical values, except for parameter changes with temperature, are at T_A = 25°C.
NOTE Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

total device (see Figure 1) (see Note 4)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
Standby supply current	RT = V_{ref}, All other inputs and outputs open	V_{CC} = 15 V		15	21	mA
		V_{CC} = 40 V		20	26	
Average supply current	DTC = 2 V			15		mA

† All typical values, except for parameter changes with temperature, are at T_A = 25°C.
NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

switching characteristics, T_A = 25°C (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output-voltage rise time	CL = 1500 pF, VC = 15 V, VCC = 15 V, See Figure 2		60	150	ns
Output-voltage fall time			35	75	

NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

PARAMETER MEASUREMENT INFORMATION

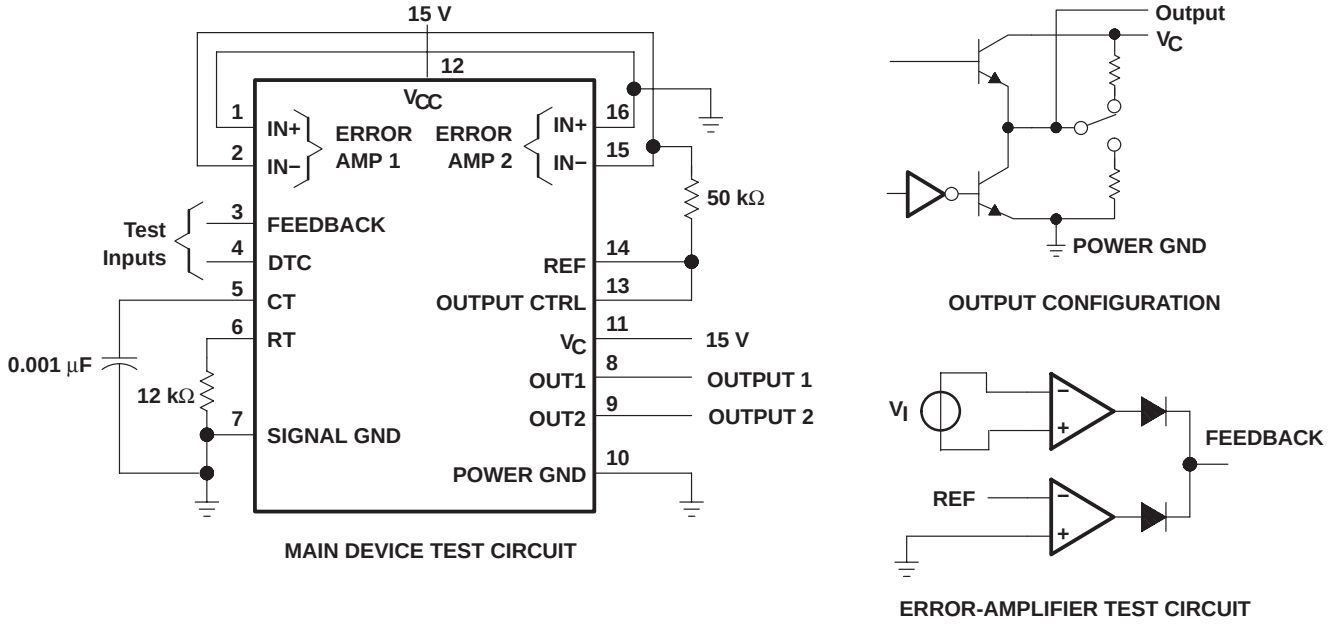


Figure 1. Test Circuits

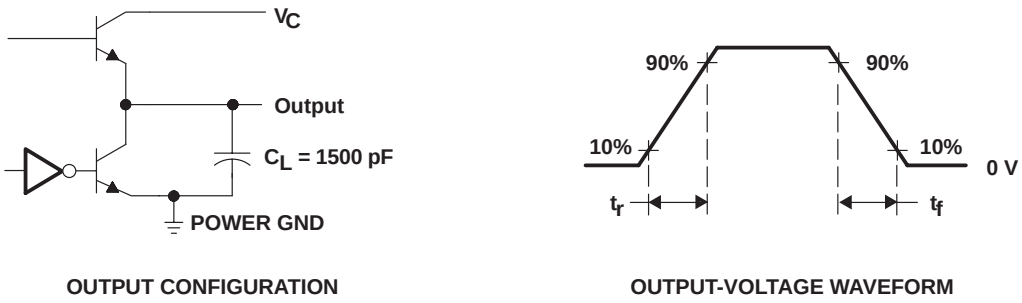
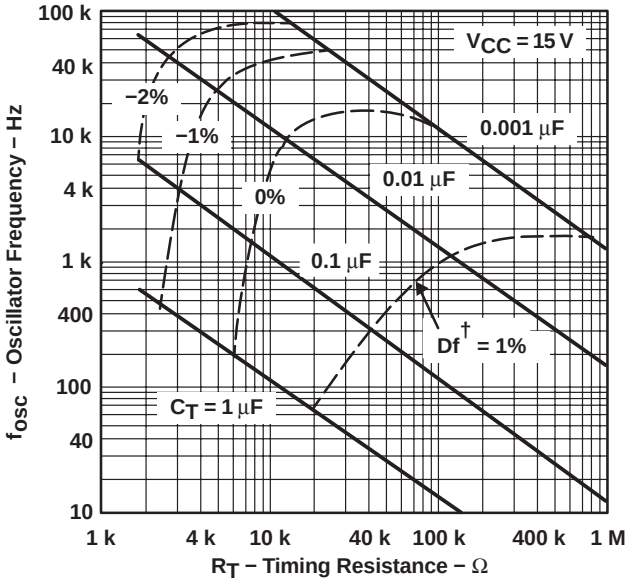


Figure 2. Switching Output Configuration and Voltage Waveform

TYPICAL CHARACTERISTICS

OSCILLATOR FREQUENCY AND FREQUENCY VARIATION† vs TIMING RESISTANCE



† Frequency variation (Δf) is the change in predicted oscillator frequency that occurs over the full temperature range.

Figure 3

AMPLIFIER VOLTAGE AMPLIFICATION vs FREQUENCY

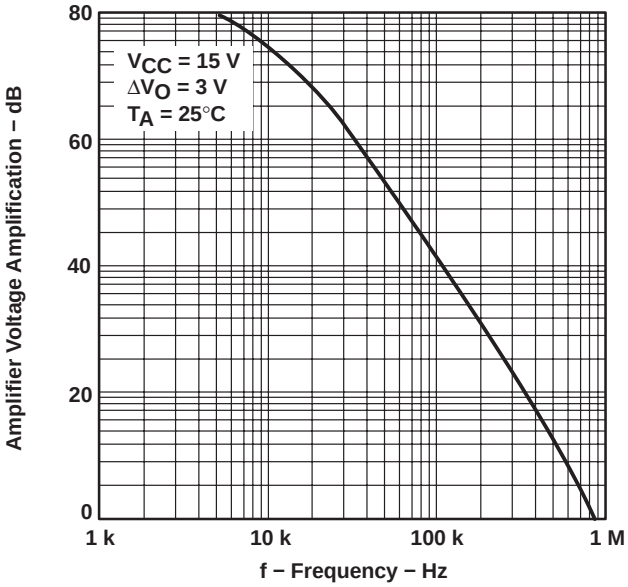


Figure 4

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL598CD	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	TL598C
TL598CDR	NRND	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL598C
TL598CDR.A	NRND	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL598C
TL598CN	NRND	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL598CN
TL598CN.A	NRND	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL598CN
TL598CNE4	NRND	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL598CN

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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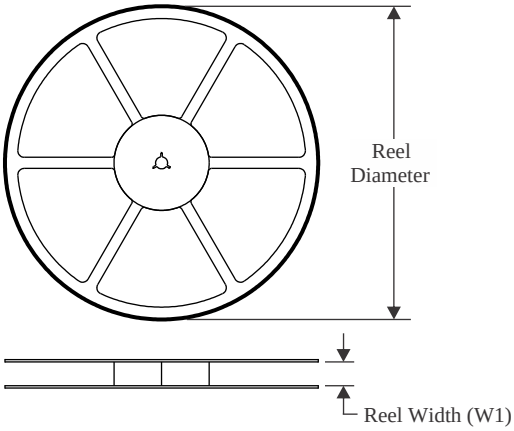
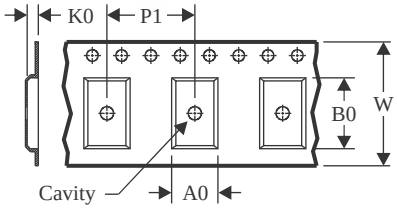
TAPE AND REEL INFORMATION

REEL DIMENSIONS

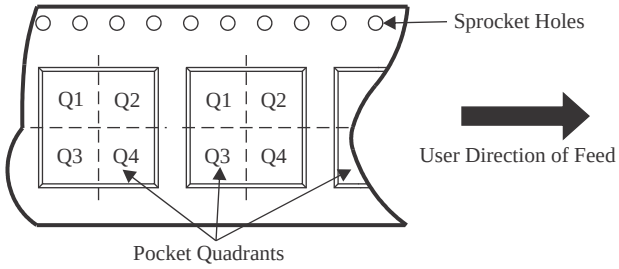


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

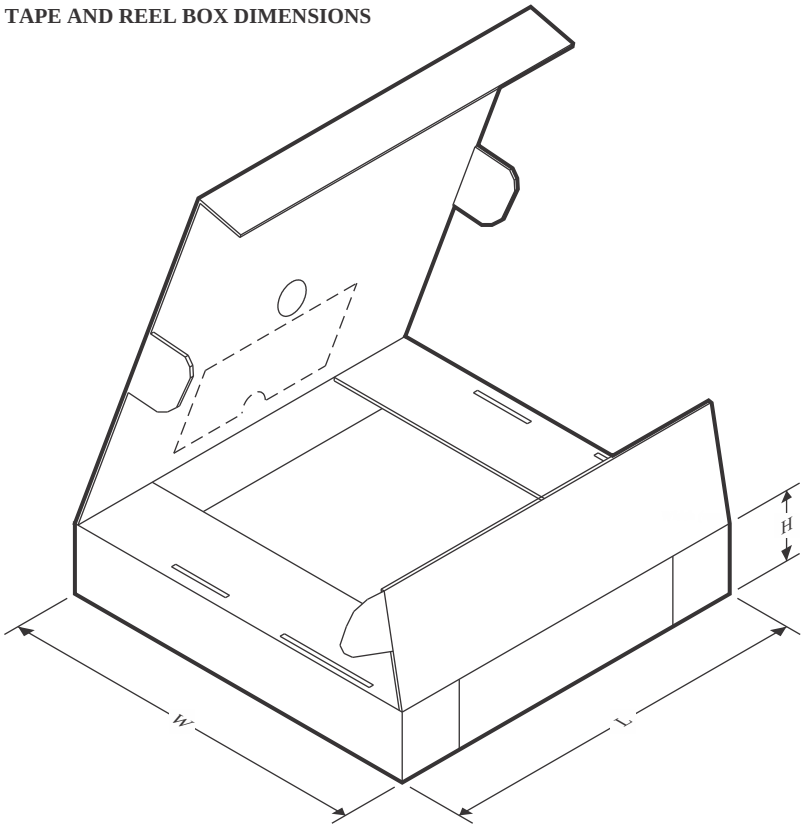
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL598CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

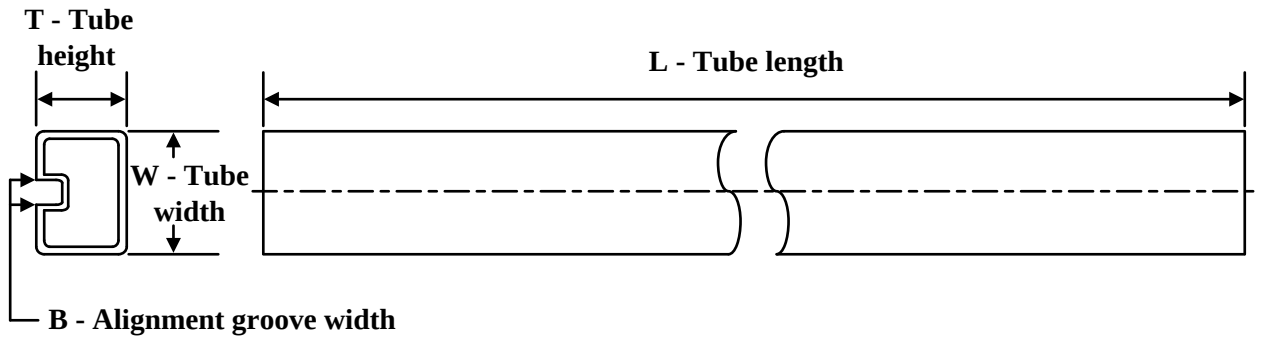
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL598CDR	SOIC	D	16	2500	353.0	353.0	32.0

TUBE



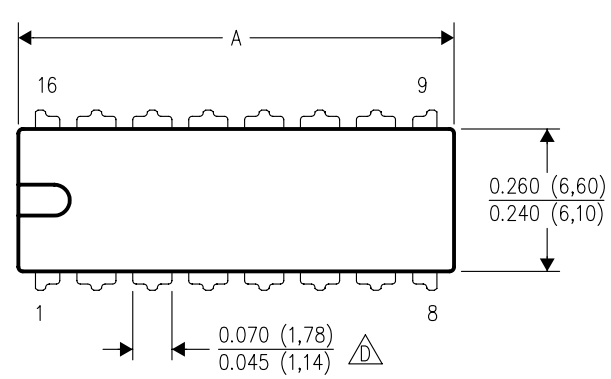
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL598CN	N	PDIP	16	25	506	13.97	11230	4.32
TL598CN.A	N	PDIP	16	25	506	13.97	11230	4.32
TL598CNE4	N	PDIP	16	25	506	13.97	11230	4.32

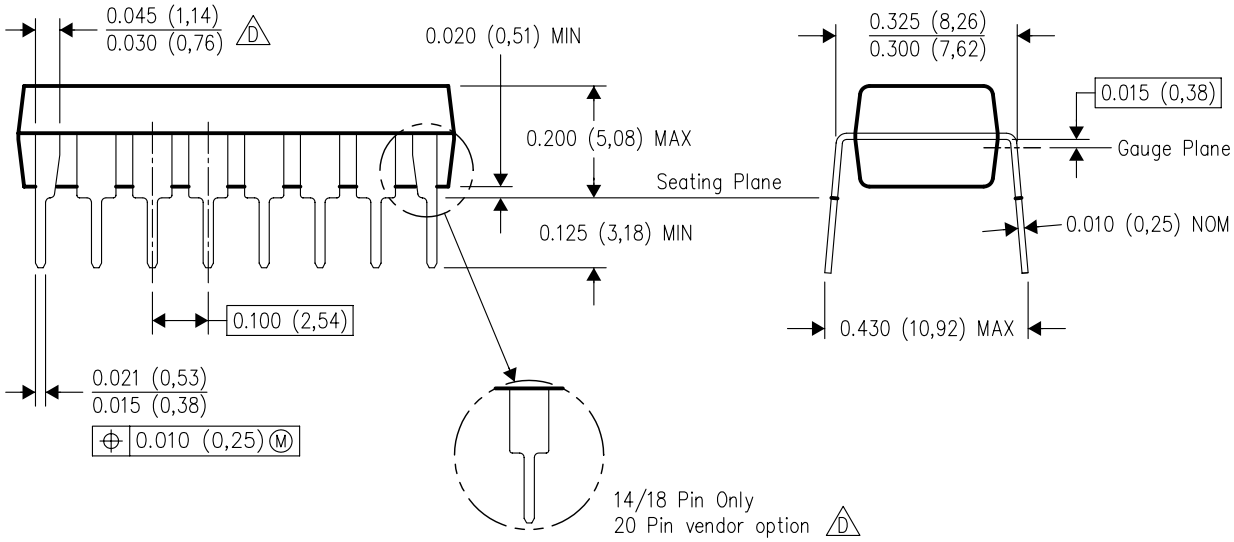
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



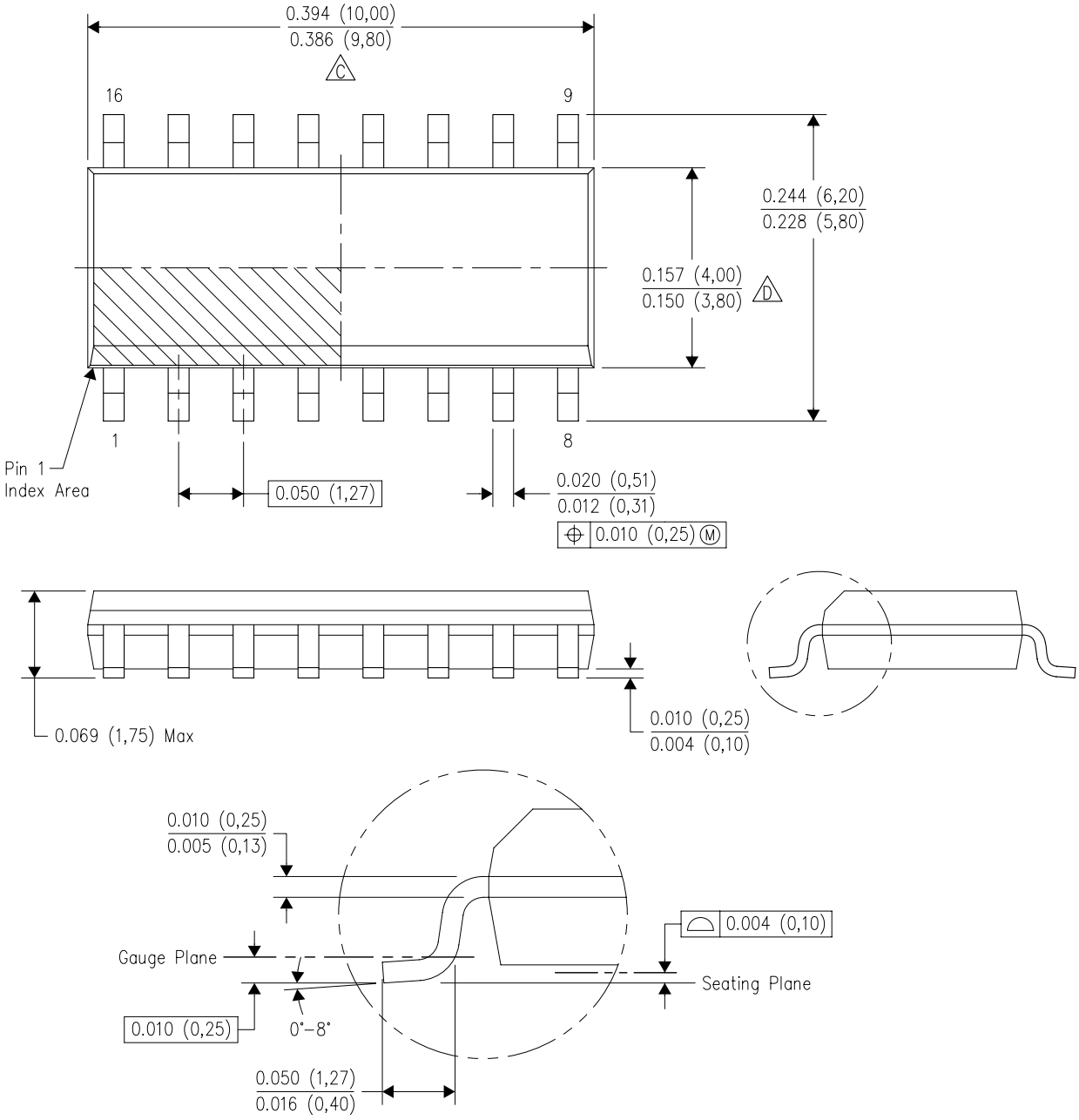
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

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